L Number	Hits	Search Text	DB	Time stamp
1	27321	electrophoretic$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:25
8	1483537	polymer$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:26
15	157995	polymeriz$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:27
22	2520	electrophoretic$4 same polymer$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:28
29	1769	electrophoretic$4 with polymer$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:28
36	42	(electrophoretic$4 with polymer$2) same polymeriz$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:36
43	444	(electrophoretic$4 with polymer$2) and (polymeriz$3 or cure or curing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:37
50	314	((electrophoretic$4 with polymer$2) and (polymeriz$3 or cure or curing)) and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:37
59	1469	(gold or au or nickel or ni or tin or sn or platinum or pt or cr or chromium) with (sputter$ and electroplat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:30
66	1221	(cu or copper) with (sputter$ and electroplat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:30
80	573	(cu or copper) with (sputter$ with electroplat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:31
73	683	(gold or au or nickel or ni or tin or sn or platinum or pt or cr or chromium) with (sputter$ with electroplat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:31
87	199	((cu or copper) with (sputter$ with electroplat$3)) with ((gold or au or nickel or ni or tin or sn or platinum or pt or cr or chromium) with (sputter$ with electroplat$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:32

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94		1	(((cu or copper) with (sputter$ with electroplat$3)) with ((gold or au or nickel or ni or tin or sn or platinum or pt or cr or chromium) with (sputter$ with electroplat$3))) and electrophoretic$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:32